1. DIMENSIONS

2. WEIGHT  $\leq 0.05$ g
3. BODY MATERIAL  LOW STRESS EPOXY
4. LEAD MATERIAL  Cu–ALLOY
5. LEAD FINISH  SOLDER PLATING
6. LEAD FORM  Z–BENDS

DIMENSIONS IN MILLIMETERS

<table>
<thead>
<tr>
<th>SYMBOL</th>
<th>P1</th>
<th>P2</th>
<th>P3</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>MIN</td>
<td>NOM</td>
<td>MAX</td>
</tr>
<tr>
<td>D1</td>
<td>3.00</td>
<td>2.50</td>
<td>2.90</td>
</tr>
<tr>
<td>E1</td>
<td>3.00</td>
<td>2.50</td>
<td>2.90</td>
</tr>
</tbody>
</table>

* WITHOUT MOLD FLASH

NOTE: REFER TO DS2 FOR OFFICIAL RELEASE DATE
Note:
1. All dimensions are in millimeters.

Title: ENG16 Package Outline Drawing
5.0 x 4.4 mm Body
0.65mm Pitch TSSOP with EPAD

Drawing No.: PSC-4761
Rev.: 03

Tolerances
Unless specified, decimal angular.
±0.20 ±2% ±0.002

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Note: Refer to CFP for official release date.